



Sheet 1 of 1

Form 1449\*

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INFORMATION DISCLOSURE STATEMENT  
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(Use several sheets if necessary)

Applicant: Kie Y. Ahn et al.

Filing Date: March 26, 2001

Group: Unknown

## U.S. PATENT DOCUMENTS

**Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
SMM	5,149,615	09/22/1992	Chakravorty, K., et al	430	313	01/08/91
	5,476,817	12/19/1995	Numata, K.	437	195	05/31/94
	5,529,956	06/25/1996	Morishita, Y.	437	195	09/28/94
	5,625,232	04/29/1997	Numata, K., et al.	257	758	07/15/94
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	5,675,187	10/07/1997	Numata, K., et al.	257	758	05/16/96
	5,893,752	04/13/1999	Zhang, J., et al.	438	687	12/22/97
	5,913,147	06/15/1999	Dubin, V., et al.	438	687	01/21/97
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## FOREIGN PATENT DOCUMENTS

**Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation Yes No
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## OTHER DOCUMENTS

(Including Author, Title, Date, Pertinent Pages, Etc.)

**Examiner Initial	
SMM	Chakravorty, K.K., et al., "High-Density Interconnection Using Photosensitive Polyimide and Electroplated Copper Conductor Lines", <u>IEEE Transactions on Components, Hybrids, and Manufacturing Technology</u> , 13(1), pp. 200-206, (March 1990)

Examiner

Date Considered

\*Substitute Disclosure Statement Form (PTO-1449)

\*\*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.